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Class 1 Non-isolated PoE Converter						
Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C17	1	470pF	CAP, CERM, 470pF, 50V, +/-5%, C0G/NP0, 0603	603	C1608C0G1H471J	TDK
C1, C2, C13	3	1000pF	CAP, CERM, 1000pF, 100V, +/-10%, X7R, 0603	603	C1608X7R2A102K	TDK
C10	1	1000pF	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	603	GRM188R71H102KA01D	MuRata
C3, C4	2	0.01uF	CAP, CERM, 0.01uF, 100V, +/-10%, X7R, 0603	603	C1608X7R2A103K	TDK
C7, C15	2	0.01uF	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	603	C1608X7R1H103K	TDK
C11	1	0.1uF	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603	603	GRM188R72A104KA35D	MuRata
C5	1	1uF	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	603	C1608X5R1C105K	TDK
C6, C14, C16	3	0.1uF	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0805	805	C2012X7R2A104K	TDK
C12	1	10uF	CAP, CERM, 10uF, 10V, +/-20%, X5R, 1206	1206	C3216X5R1A106M	TDK
C18	0	DNP	CAP, CERM, 10uF, 10V, +/-20%, X5R, 1206	1206	C3216X5R1A106M	TDK
C9	1	2.2uF	CAP, CERM, 2.2uF, 100V, +/-10%, X7R, 1210	1210	GRM32ER72A225KA35L	MuRata
C8	1	10uF	CAP, AL, 10uF, 63V, +/-20%, 1.5 ohm, SMD	SMT Radial D	EEE-FK1J100P	Panasonic
D1, D2	2		Diode, Switching-Bridge, 100V, 0.8A, MiniDIP	MiniDIP	HD01-T	Diodes Inc.
D3, D4	0	DNP	Diode, Switching-Bridge, 100V, 0.5A, 3x0.6x3mm	3x0.6x3mm	SBR05M100BLP	Diodes Inc.
D5	1	58V	Diode, TVS, Uni, 58V, 400W, SMA	SMA	SMAJ58A	Diodes Inc.
D6	0	DNP	Diode, Schottky, 100V, 1A, SMB	SMB	MBRS1100T3G	ON Semiconductor
D7	1		Diode, Schottky, 100V, 1A, SMB	SMB	MBRS1100T3G	ON Semiconductor
J1, J2	2		RJ-45, Right Angle, No LED, tab up	16.26x14.54x15.75	1-406541-1	AMP
J3, J4	2		Header, 100mil, 2x1, Tin plated, TH	Header, 2 PIN, 100mil, Tin	PEC02SAAN	Sullins Connector Solutions
L1, L2, L4, L5	4		Ferrite Bead, 220 ohm @ 100 MHz, 2.2 A, 0603	603	MPZ1608S221A	TDK
L3	1	68uH	Inductor, Shielded Drum Core, Ferrite, 68uH, 1.75A, 0.21 ohm, SMD	MSS1038	MSS1038-683MLB	Coilcraft
Q1	1		MOSFET, N-CH, 100V, 2.1A, SOT-363	SOT-363	SI1480DH-T1-GE3	Vishay-Siliconix
R1, R2, R3, R4	4	75	RES, 75.0 ohm, 1%, 0.1W, 0603	603	CRCW060375R0FKEA	Vishay-Dale
R5	1	0	RES, 0 ohm, 5%, 0.1W, 0603	603	ERJ-3GEY0R00V	Panasonic
R10	1	243	RES, 243 ohm, 1%, 0.1W, 0603	603	CRCW0603243RFKEA	Vishay-Dale
R15	1	12.1k	RES, 12.1k ohm, 1%, 0.1W, 0603	603	CRCW060312K1FKEA	Vishay-Dale
R17	1	3.24k	RES, 3.24k ohm, 1%, 0.1W, 0603	603	CRCW06033K24FKEA	Vishay-Dale
R11	1	20.0k	RES, 20.0k ohm, 1%, 0.1W, 0603	603	CRCW060320K0FKEA	Vishay-Dale
R7	1	24.9k	RES, 24.9k ohm, 1%, 0.1W, 0603	603	CRCW060324K9FKEA	Vishay-Dale
R12, R13	2	32.4k	RES, 32.4k ohm, 1%, 0.1W, 0603	603	CRCW060332K4FKEA	Vishay-Dale
R6, R9	2	100k	RES, 100k ohm, 1%, 0.1W, 0603	603	CRCW0603100KFKEA	Vishay-Dale
R8	1	200k	RES, 200k ohm, 1%, 0.1W, 0603	603	CRCW0603200KFKEA	Vishay-Dale
R14	1	237k	RES, 237k ohm, 1%, 0.1W, 0603	603	CRCW0603237KFKEA	Vishay-Dale
T1	1		Transformer, 350uH, SMT	358x236x500mil	H2019FNLT	Pulse Engineering
U1	1		80V, 600mA Constant On-Time Buck Switching Regulator, 10-pin MSOP, Pb-Free	MUB10A	LM5006MMX/NOPB	Texas Instruments
U2	1		IEEE 802.3at PoE High-Power PD Interface, DDA0008E	DDA0008E	TPS2378DDA	Texas Instruments

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